

HV9861A

LED Driver with Average-Mode Constant Current Control

Features

- Fast Average Current Control
- Programmable Constant Off-Time Switching
- PWM/Linear Dimming Input
- · Output Short Circuit Protection with Skip Mode
- Ambient Operating Temperature -40°C to +125°C
- Pin-Compatible with the HV9910B and HV9961

Applications

- DC/DC or AC/DC LED Driver Applications
- LED Back-Light Driver for LCD Displays
- General Purpose Constant Current Source
- · LED Signage and Displays
- Architectural and Decorative LED Lighting
- LED Street Lighting

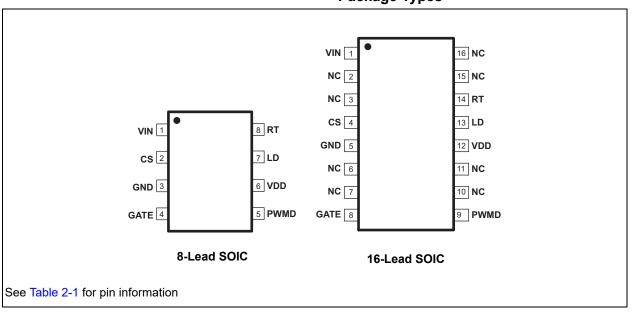
Description

HV9861A is a patented, average-mode, constantcurrent control, LED driver IC operating in a constant off-time mode. Unlike the HV9910B, this control IC does not produce a peak-to-average error, which therefore greatly improves the accuracy, line and load regulation of the LED current without any need for loop compensation or high-side current sensing. The output LED current accuracy is $\pm 3\%$.

The IC is equipped with a current limit comparator for hiccup-mode output short circuit protection. Internal over-temperature protection is provided. The internally regulated voltage (V_{DD}) for the HV9861A is 7.5V.

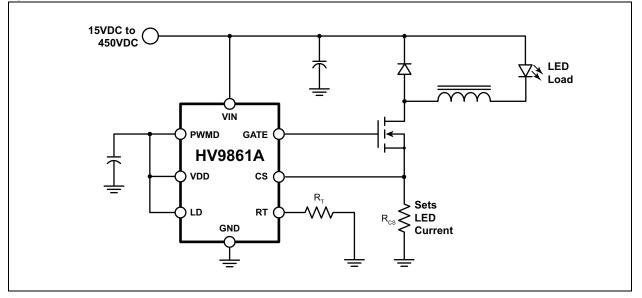
The IC can be powered from a 15 - 450V supply. A PWM dimming input is provided that accepts an external control TTL-compatible signal. The output current can be programmed by an internal 270 mV reference, or controlled externally through a 0 - 1.5V dimming input.

HV9861A is pin-to-pin compatible with the HV9910B and HV9961, and can be used as a drop-in replacement for many applications to improve the LED current accuracy and regulation.

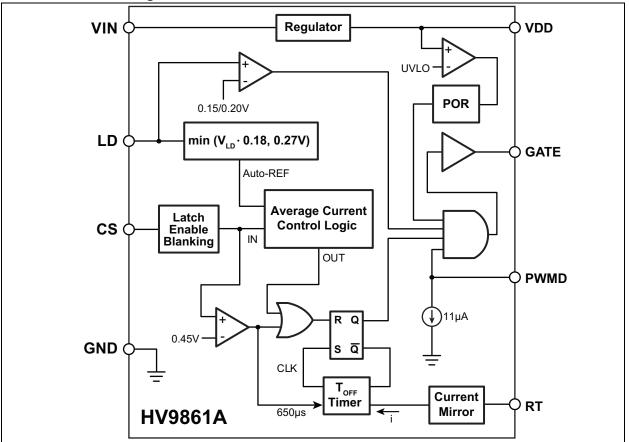


Package Types

Typical Application Circuit



Functional Block Diagram



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1.0 ELECTRICAL CHARACTERISTICS

ABSOLUTE MAXIMUM RATINGS

V _{IN} to GND V _{DD} to GND	
LD, PWMD, GATE to GND	–0.3V to (V _{DD} + 0.3V)
CS, RT to GND	–0.3V to 5.0V
Operating temperature	–40°C to +125°C
Storage temperature	–65°C to +150°C
Continuous power dissipation ($T_A = +25^{\circ}C$)	
8-lead SOIC	650 mW
16-lead SOIC	1000 mW

Note: Stresses above those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at those or any other conditions, above those indicated in the operational listings of this specification, is not implied. Exposure to maximum rating conditions for extended periods may affect device reliability.

1.1 ELECTRICAL SPECIFICATIONS

Parameter	Symbol	Min	•	Max	Units	Conditions		
	Symbol	IVIIII	Тур	IVIAX	Units	Conditions		
Input								
Input DC Supply Voltage Range (<mark>Note 2</mark>)	V _{INDC}	15		450	V	DC Input Voltage (Note 3)		
Shut-down Mode Supply Current	I _{INSD}		0.5	1.1	mA	Pin PWMD to GND (Note 3)		
Internal Regulator								
Internally Regulated Voltage	V _{DD}	7.25	7.50	8.20	V	500 pF at GATE; R _T = 226 kΩ		
Line Regulation of V _{DD}	ΔV_{DD} , line			1	V	V _{IN} = 15 - 450V, 500 pF at GATE; R _T = 226 kΩ		
Load Regulation of V _{DD}	ΔV_{DD} , load	_	_	100	mV	I _{DD(ext)} = 0 - 1 mA, 500 pF at GATE; RT = 226 kΩ		
V _{DD} Under-voltage Lockout Threshold	UVLO	6.45		_	V	V _{IN} rising (Note 3)		
V _{DD} Under-voltage Lockout Hysteresis	∆UVLO	_	500	_	mV	V _{IN} falling		
V _{DD} Voltage Margin	$\Delta V_{DD(UV)}$	500	_	—	mV	$\Delta V_{DD(UV)} = V_{DD} - UVLO (Note 3)$		
Maximum Input Current		3.5	_			V _{IN} = 15V, T _A = 25°C (Note 4)		
(limited by UVLO)	I _{IN,MAX}	1.5	_	_	mA	V _{IN} = 15V, T _A = 125°C (Note 4)		
PWM Dimming								
PWMD Input Low Voltage	V _{EN(lo)}	—	—	0.8	V	V _{IN} = 15 - 450V (Note 3)		
PWMD Input High Voltage	V _{EN(hi)}	2.2	_	_	V	V _{IN} = 15 - 450V (Note 3)		
Internal Pull-down Current at PWMD	I _{EN}	8	_	15	μA	V _{PWMD} = 0.8V		

TABLE 1-1: ELECTRICAL CHARACTERISTICS (Note 1)

Parameter	Symbol	Min	Тур	Мах	Units	Conditions
Average Current Sense Log	gic					
Current Sense Reference Voltage	V _{CST}	262	_	280	mV	
LD-to-CS Voltage Ratio	A _{V(LD)}	0.175	_	0.182		
LD-to-CS Voltage Offset	A _V • V _{LD(OFFSET)}	-15	_	12	mV	$V_{OFFSET} = V_{CS} - (A_{V(LD)} \cdot V_{LD});$ $V_{LD} = 1.2V$
CS Threshold Temperature Regulation	$\Delta V_{CS(TEMP)}$	Ι	—	5	mV	Note 4
LD Input Voltage, Shutdown	V _{LD(OFF)}		150		mV	V _{LD} falling
LD Input Voltage, Enable	V _{LD(EN)}	_	200	—	mV	V _{LD} rising
Current Sense Blanking Interval	T _{BLANK}	140	_	290	ns	Note 3
Minimum On-time	T _{ON(MIN)}			760	ns	$V_{CS} = V_{CST} + 30 \text{ mV}$
Maximum Steady-state Duty Cycle	D _{MAX}	80	—	_	%	Reduction in output LED current may occur beyond this duty cycle (Note 1)
Short Circuit Protection						
Hiccup Threshold Voltage	V _{CSH}	410		510	mV	Note 3
Current Limit Delay CS-to-GATE	T _{DELAY}	_	_	150	ns	V _{CS} = V _{CSH} + 30 mV
Short Circuit Hiccup Time	T _{HICCUP}	400		850	μs	
Minimum On-time (Short Circuit)	T _{ON(MIN)SC}		—	430	ns	V _{CS} = 4V
TOFF Timer						
Off time -	-	32	40	48		R _T = 1 MΩ
Off-time	T _{OFF}	8	10	12	μs	R _T = 226 kΩ
GATE Driver						
Sourcing Current	I _{SOURCE}	0.165		_	Α	V _{GATE} = 0V, V _{DD} = 7.5V
Sinking Current	I _{SINK}	0.165		_	А	$V_{GATE} = V_{DD}, V_{DD} = 7.5V$
Output Rise Time	t _{RISE}		30	50	ns	C _{GATE} = 500 pF, V _{DD} = 7.5V
Output Fall Time	t _{FALL}	—	30	50	ns	C _{GATE} = 500 pF, V _{DD} = 7.5V
Over-Temperature Protection	on					
Shut-down Temperature	T _{SD}	128	140		°C	Note 4
Hysteresis	ΔT_{SD}	_	20		°C	Note 4

TABLE 1-1. ELECTRICAL CHARACTERISTICS (CONTINUED)(Note 1)

2: Also limited by package-power dissipation limit; Whichever is lower.

3: Applies over the full operating ambient temperature range of -40° C < T_A < +125°C.

4: For design guidance only.

TABLE 1-2: THERMAL RESISTANCE

Package	Symbol	Min	Тур	Max	Units	Conditions
8-Lead SOIC	θ_{JA}	_	101	—	°C/W	
16-Lead SOIC	θ_{JA}	—	83	—	°C/W	

2.0 PIN DESCRIPTION

The details on the pins of HV9861A are listed on Table 2-1. Refer to Package Types for the location of pins.

Pi	n #	Function	Description
8-Lead SOIC	16-Lead SOIC	Function	Description
1	1	VIN	Input of a 15 - 450V linear regulator.
2	4	CS	Current sense pin used to sense the FET current by means of an external sense resistor.
3	5	GND	Ground return for all internal circuitry. This pin must be electrically connected to the ground of the power train.
4	8	GATE	Output GATE driver for an external N-channel power MOSFET.
5	9	PWMD	PWM-dimming input of the IC. When this pin is pulled to GND, the gate driver is turned off. When the pin is pulled high, the gate driver operates normally.
6	12	VDD	Power supply pin for all internal circuits. It must be bypassed with a low-ESR capacitor to GND (at least 0.1 $\mu F).$
7	13	LD	Linear-dimming input. Sets the current sense threshold as long as the voltage at this pin is less than 1.5V. If voltage at LD falls below 150 mV, the GATE output is disabled. The GATE signal recovers at 200 mV at LD.
8	14	RT	A resistor connected between this pin and GND programs the GATE off-time.
-	2, 3, 6, 7, 10, 11, 15, 16	NC	No connection.

TABLE 2-1: PIN DESCRIPTION

3.0 APPLICATION INFORMATION

Peak-current control (as in the HV9910B) of a buck converter is the most economical and simple way to regulate its output current. However, this method suffers accuracy and regulation problems that arise from the so-called peak-to-average current error, contributed to by the current ripple in the output inductor and the propagation delay in the current-sense comparator. The full inductor-current signal is unavailable for direct sensing at the ground potential in a buck converter when the control switch is referenced to the same ground potential. While it is very simple to detect the peak current in the switch, controlling the average inductor current is usually implemented by level translating the sense signal from the positive supply rail. Though this is practical for relatively low input voltage, this type of average-current control may become excessively complex and expensive in off line AC or other high-voltage DC applications.

HV9861A employs a patented control scheme, achieving fast and very accurate control of average current in the buck inductor through sensing the switch current only. No compensation of the current-control loop is required. The LED current response to PWMD input is similar to that of the HV9910B. The inductorcurrent ripple amplitude does not affect this control scheme significantly. Therefore, the LED current is independent of the variation in inductance, switching frequency, or output voltage. Constant off-time control of the buck converter is used for stability and to improve the LED-current regulation over a wide range of input voltages. (Note that, unlike the HV9910B, this IC does not support the constant-frequency mode of operation.)

3.1 OFF Timer

The timing resistor connected to RT determines the offtime of the gate driver, and it must be wired to GND. Wiring this resistor to GATE as with the HV9910B is no longer supported. The equation governing the off-time of the GATE output is given by:

$$T_{OFF}(\mu s) = \frac{R_T(k\Omega)}{25} + 0.3$$

Within the range of 30 k $\Omega \le R_T \le 1.0 M\Omega$.

3.2 Average Current Control Feedback and Output Short Circuit Protection

The current through the switching MOSFET source is averaged and used to give constant-current feedback. This current is detected using a sense resistor at the CS pin. The feedback operates in a fast open-loop mode. No compensation is required. Output current is programmed simply as:

$$I_{LED} = \frac{0.27V}{R_{CS}}$$

When the voltage at the LD input $V_{LD} \ge 1.5V$. Otherwise:

$$I_{LED} = \frac{V_{LD} \cdot 0.18}{R_{CS}}$$

The above equations are only valid for continuous conduction of the output inductor. It is a good practice to design the inductor such that the switching peak-to-peak ripple current in it is 30~40% of its average DC full-load current. Hence, the recommended inductance can be calculated as:

$$L = \frac{V_{O(MAX)} \cdot T_{OFF}}{0.4 \cdot I_{O(MAX)}}$$

The duty-cycle range of the current control feedback is limited to D \leq 0.8. A reduction in the LED current may occur when the LED string voltage V_O is greater than 80% of the input voltage V_{IN} of the HV9861A LED driver.

Reducing the output LED voltage V_O below V_{O(MIN)} = $V_{IN} \cdot D_{MIN}$, where D_{MIN} = 760 ns/(T_{OFF} +760 ns), may also result in the loss of regulation of the LED current. However, this condition causes an increase in the LED current and can potentially trip the short-circuit protection comparator.

A typical output characteristic of the HV9861A LED driver is shown in Figure 3-1. The corresponding HV9910B characteristic is given for comparison.

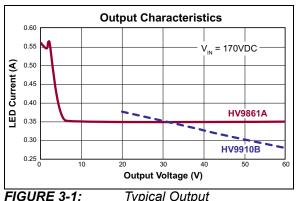


FIGURE 3-1: Typical Output Characteristic of an HV9861A LED Driver.

The short circuit protection comparator trips when the voltage at CS exceeds 0.45V. When this occurs, the GATE off-time $T_{HICCUP} = 650 \ \mu s$ is generated to prevent stair-casing of the inductor current, and potentially

its saturation, due to insufficient output voltage. The typical short-circuit current is shown in the waveform of Figure 3-2.

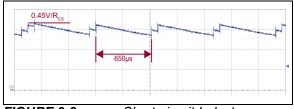


FIGURE 3-2: Short-circuit Inductor Current.

A leading-edge blanking delay is provided at CS to prevent false triggering of the current feedback and the short circuit protection.

3.3 Linear Dimming

When the voltage at LD falls below 1.5V, the internal 270 mV reference to the constant-current feedback becomes overridden by $V_{LD} \cdot 0.18$. As long as the current in the inductor remains continuous, the LED current is given by the equation in Section 3.2 "Average Current Control Feedback and Output Short Circuit Protection". However, when V_{LD} falls below 150mV, the GATE output becomes disabled. The GATE signal recovers, when V_{LD} exceeds 200 mV. This is required in some applications to be able to shut the LED lamp off with the same signal input that controls the brightness. The typical linear dimming response is shown in Figure 3-3.

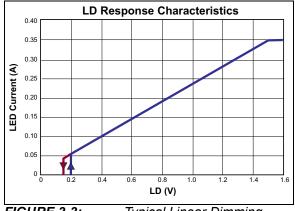


FIGURE 3-3: Typical Linear Dimming Response of an HV9861A LED Driver.

The linear dimming input could also be used for "mixedmode" dimming to expand the dimming ratio. In such case a pulse-width modulated signal of a measured amplitude below 1.5V should be applied at LD.

3.4 Input Voltage Regulator

HV9861A can be powered directly from a 15 - 450VDC supply through its VIN input. When this voltage is applied at the VIN pin, the HV9861A maintains a constant 7.5V level at VDD. This voltage can be used to power the IC and external circuitry connected to VDD within the rated maximum current or within the thermal ratings of the package, whichever limit is lower. The VDD pin must be bypassed by a low ESR capacitor to provide a low impedance path for the high frequency current of the GATE output. The HV9861A can also be powered through the VDD pin directly with a voltage greater than the internally regulated 7.5V, but less than 12V.

Despite the instantaneous voltage rating of 450V, continuous voltage at VIN is limited by the power dissipation in the package. For example, when these ICs draw $I_{IN} = 3.0$ mA from the VIN input, and the 8-lead SOIC package is used, the maximum continuous voltage at VIN is limited to the following:

$$V_{IN(MAX)} = \frac{T_{J(MAX)} - T_A}{R_{\theta, JA} \cdot I_{IN}} = 330V$$

In this instance, the ambient temperature $T_A = 25^{\circ}C$, the maximum working junction temperature $T_{J(MAX)} = 125^{\circ}C$, and the junction-to-ambient thermal resistance $R_{\theta,JA} = 101^{\circ}C/W$.

In such cases, when it is needed to operate the HV9861A from a higher voltage, a resistor or a Zener diode can be added in series with the VIN input to divert some of the power loss from the IC. In the above example, using a 100V Zener diode will allow the circuit to work up to 430V. The input current drawn from the VIN pin is represented by the following equation:

$$I_{IN} \approx 1.0 mA + Q_G \cdot f_s$$

In the above equation, f_S is the switching frequency, and Q_G is the GATE charge of the external FET obtained from the manufacturer's data sheet.

3.5 GATE Output

The GATE output of HV9861A is used to drive an external MOSFET. The gate charge, Q_G , of the external MOSFET should be less than 25 nC for switching frequencies ≤ 100 kHz and less than 15 nC for switching frequencies >100 kHz.

3.6 **PWM** Dimming

Due to the fast open-loop response of the averagemode, current-control loop of the HV9861A, the PWM dimming performance nearly matches that of the HV9910B. The inductor current waveform comparison is shown in Figure 3-4.

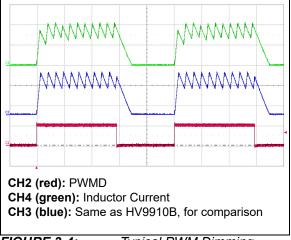
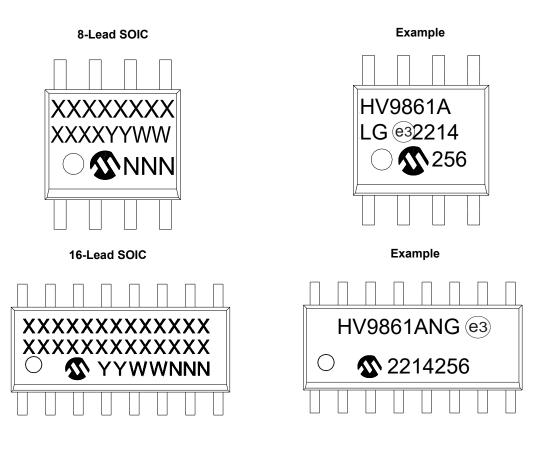


FIGURE 3-4: Typical PWM Dimming Response of an HV9861A LED Driver.

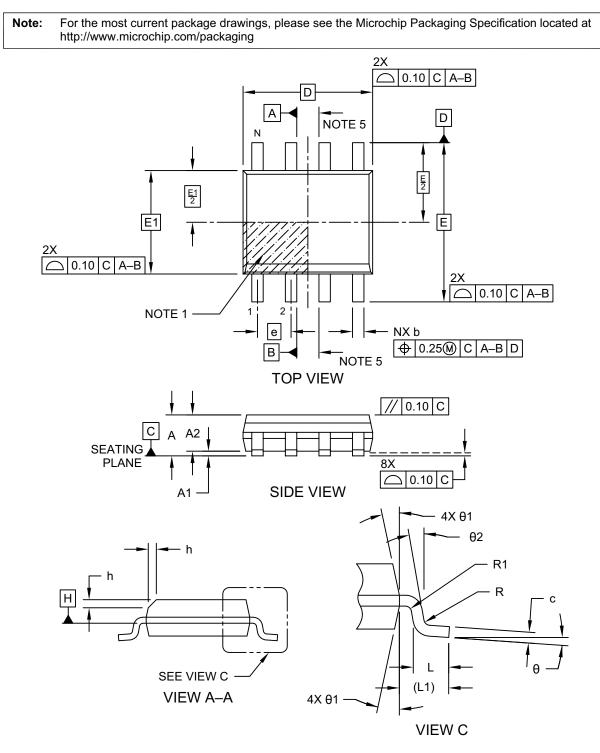
The rising and falling edges are limited by the current slew rate in the inductor. The first switching cycle is terminated upon reaching the 270 mV ($V_{LD} \cdot 0.18$) level at CS. The circuit is further reaching its steady-state within 3–4 switching cycles regardless of the switching frequency.

4.0 PACKAGING INFORMATION

4.1 Package Marking Information



Legend:	 XXX Product code or customer-specific information Y Year code (last digit of calendar year) YY Year code (last 2 digits of calendar year) WW Week code (week of January 1 is week '01') NNN Alphanumeric traceability code (e3) Pb-free JEDEC[®] designator for Matte Tin (Sn) * This package is Pb-free. The Pb-free JEDEC designator (e3) can be found on the outer packaging for this package. , ▲, ▼ Pin one index is identified by a dot, delta up, or delta down (triangle mark).
t c	the event the full Microchip part number cannot be marked on one line, it will e carried over to the next line, thus limiting the number of available naracters for customer-specific information. Package may or may not include e corporate logo.
ι	nderbar (_) and/or Overbar (⁻) symbol may not be to scale.

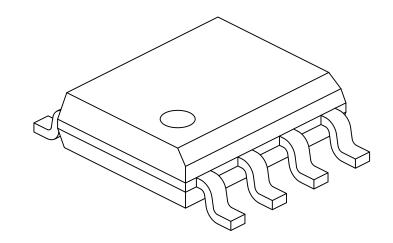


8-Lead Plastic Small Outline (SN) - Narrow, 3.90 mm (.150 In.) Body [SOIC]

Microchip Technology Drawing No. C04-057-SN Rev J Sheet 1 of 2

8-Lead Plastic Small Outline (SN) - Narrow, 3.90 mm (.150 In.) Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



	MILLIMETERS			
Dimension Limits		MIN	NOM	MAX
Number of Pins	Ν		8	
Pitch	е		1.27 BSC	
Overall Height	А	-	-	1.75
Molded Package Thickness	A2	1.25	-	-
Standoff §	A1	0.10	-	0.25
Overall Width	Е		6.00 BSC	
Molded Package Width	E1	3.90 BSC		
Overall Length	D		4.90 BSC	
Chamfer (Optional)	h	0.25	-	0.50
Foot Length	L	0.40	-	1.27
Footprint	L1		1.04 REF	
Lead Thickness	С	0.17	-	0.25
Lead Width	b	0.31	-	0.51
Lead Bend Radius	R	0.07	-	-
Lead Bend Radius	R1	0.07 – –		
Foot Angle	θ	0° – 8°		
Mold Draft Angle	θ1	5° – 15°		
Lead Angle	θ2	0°	_	8°

Notes:

1. Pin 1 visual index feature may vary, but must be located within the hatched area.

2. § Significant Characteristic

3. Dimensions D and E1 do not include mold flash or protrusions. Mold flash or protrusions shall not exceed 0.15mm per side.

4. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

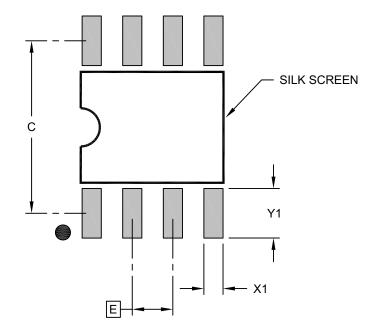
REF: Reference Dimension, usually without tolerance, for information purposes only.

5. Datums A & B to be determined at Datum H.

Microchip Technology Drawing No. C04-057-SN Rev J Sheet 2 of 2

8-Lead Plastic Small Outline (SN) - Narrow, 3.90 mm (.150 In.) Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

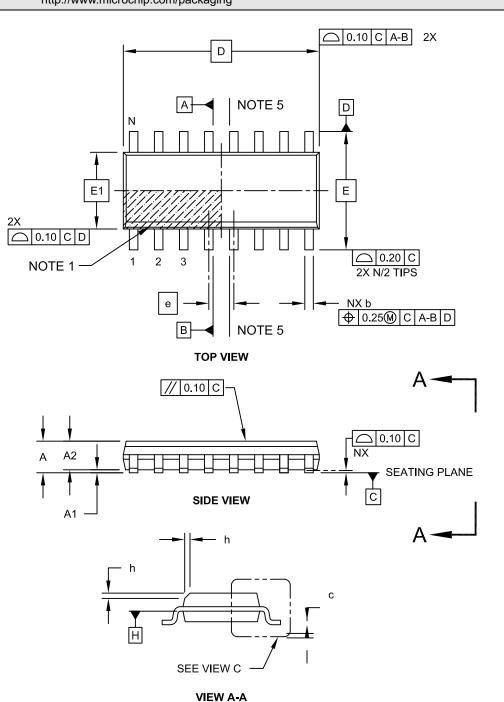
	Units	Ν	/ILLIMETER	S
Dimension	Limits	MIN	NOM	MAX
Contact Pitch	E		1.27 BSC	
Contact Pad Spacing	С		5.40	
Contact Pad Width (X8)	X1			0.60
Contact Pad Length (X8)	Y1			1.55

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing C04-2057-SN Rev J



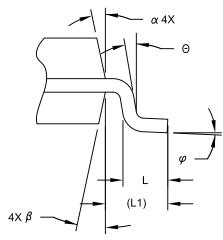
16-Lead Plastic Small Outline (SL) - Narrow, 3.90 mm Body [SOIC]

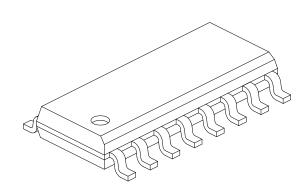
Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging

Microchip Technology Drawing No. C04-108C Sheet 1 of 2

16-Lead Plastic Small Outline (SL) - Narrow, 3.90 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging





VIEW C

	MILLIMETERS			
Dimension Limits		MIN	NOM	MAX
Number of Pins	N		16	
Pitch	е		1.27 BSC	
Overall Height	A	-	-	1.75
Molded Package Thickness	A2	1.25	-	-
Standoff §	A1	0.10	-	0.25
Overall Width	E		6.00 BSC	
Molded Package Width	E1		3.90 BSC	
Overall Length	D		9.90 BSC	
Chamfer (Optional)	h	0.25	-	0.50
Foot Length	L	0.40	-	1.27
Footprint	L1		1.04 REF	
Lead Angle	Θ	0°	-	-
Foot Angle	φ	0°	-	8°
Lead Thickness	С	0.10	-	0.25
Lead Width	b	0.31	-	0.51
Mold Draft Angle Top	α	5°	-	15°
Mold Draft Angle Bottom	β	5°	-	15°

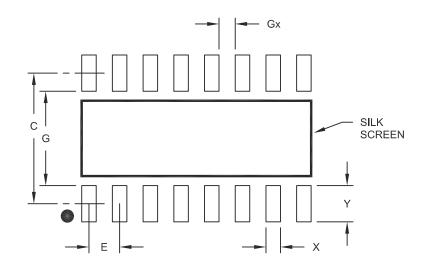
Notes:

- 1. Pin 1 visual index feature may vary, but must be located within the hatched area.
- 2. § Significant Characteristic
- 3. Dimension D does not include mold flash, protrusions or gate burrs, which shall not exceed 0.15 mm per end. Dimension E1 does not include interlead flash or protrusion, which shall not exceed 0.25 mm per side.
- 4. Dimensioning and tolerancing per ASME Y14.5M
 - BSC: Basic Dimension. Theoretically exact value shown without tolerances.
 - REF: Reference Dimension, usually without tolerance, for information purposes only.
- 5. Datums A & B to be determined at Datum H.

Microchip Technology Drawing No. C04-108C Sheet 2 of 2

16-Lead Plastic Small Outline (SL) - Narrow, 3.90 mm Body [SOIC]

Note: For the most current package drawings, please see the Microchip Packaging Specification located at http://www.microchip.com/packaging



RECOMMENDED LAND PATTERN

	Units		MILLIMETERS		
Dimension	Limits	MIN	NOM	MAX	
Contact Pitch	E		1.27 BSC		
Contact Pad Spacing	С		5.40		
Contact Pad Width	Х			0.60	
Contact Pad Length	Y			1.50	
Distance Between Pads	Gx	0.67			
Distance Between Pads	G	3.90			

Notes:

1. Dimensioning and tolerancing per ASME Y14.5M

BSC: Basic Dimension. Theoretically exact value shown without tolerances.

Microchip Technology Drawing No. C04-2108A

NOTES:

APPENDIX A: REVISION HISTORY

Revision B (July 2022)

- Updated the Electrical Characteristics table (Table 1-1).
- Updated Section 4.0 "Packaging Information" with the latest package drawings.
- Minor changes throughout the document.

Revision A (December 2014)

• Original Release of this Document.

NOTES:

PRODUCT IDENTIFICATION SYSTEM

To order or obtain information, e.g., on pricing or delivery, refer to the factory or the listed sales office.

PART NO.	<u>xx</u> - <u>x</u> - <u>x</u>	E	xamples:	
	ackage Environmental Media ptions Type	a)) HV9861ALG-G:	8-lead SOIC package, Lead (Pb)-free, RoHS- compliant, 3300/Reel
Device:	HV9861A= LED Driver with Average-Mode Constant Current Control	b)) HV9861ANG-G	16-lead SOIC package, Lead (Pb)-free, RoHS - compliant, 45/Tube
Package:	LG = 8-lead SOIC NG = 16-lead SOIC			
Environmental	G = Lead (Pb)-free/RoHS-compliant package			
Media Type:	(blank) = Reel for LG package, Tube for NG package			
		- 1		

NOTES:

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- Microchip believes that its family of products is secure when used in the intended manner, within operating specifications, and under normal conditions.
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